



Material Content Data Sheet



Sales Product Name	TLE5205-2GP			Issued		28. August 2013		
MA#	MA000543914							
Package	PG-DSO-20-37			Weight*		1.15 g		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [g]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.000	0.00		0	3600
leadframe	inorganic material	phosphorus	7723-14-0	0.000	0.00		0	
	non noble metal	zinc	7440-66-6	0.000	0.00		0	
	non noble metal	iron	7439-89-6	0.000	0.00		0	
	non noble metal	copper	7440-50-8	0.000	0.00		0	3600
wire	noble metal	gold	7440-57-5	0.000	0.00		0	3600
encapsulation	organic material	carbon black	1333-86-4	0.000	0.00		0	
	plastics	epoxy resin	-	0.000	0.00		0	
	inorganic material	silicondioxide	60676-86-0	0.000	0.00		0	3600
leadfinish	non noble metal	tin	7440-31-5	0.000	0.00		0	3600
solder	noble metal	silver	7440-22-4	0.000	0.00		0	
	non noble metal	tin	7440-31-5	0.000	0.00		0	
	non noble metal	lead	7439-92-1	0.000	0.00		0	3600
*deviation	< 10%	Sum in total:			0,00			21601

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com